

SOT941-2

plastic thermal enhanced very thin quad flat package; no leads; 112 terminals; UTLP based; body 7 x 7 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN112U
Package type industry code	HVQFN112U
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	1	-	1	1	mm
A ₂	package height	[tbd]	-	0.9	[tbd]	mm
n ₂	actual quantity of termination	-	-	112	-	

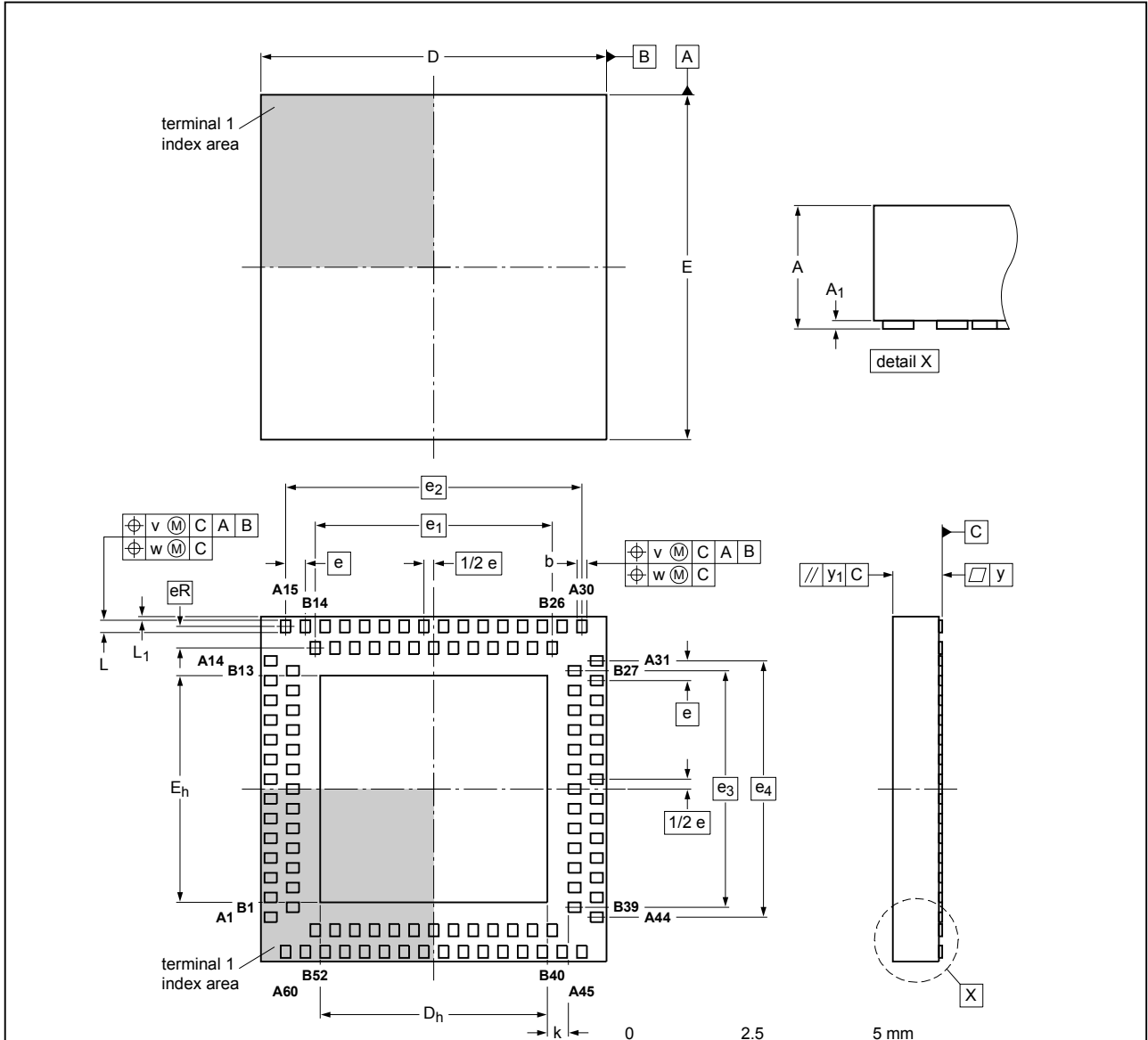


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2. Package outline

HVQFN112U: plastic thermal enhanced very thin quad flat package; no leads; 112 terminals; UTLP based; body 7 x 7 x 0.9 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	b	D	D _h	E	E _h	e	e ₁	e ₂	e ₃	e ₄	eR	k	L	L ₁	v	w	y	y ₁
mm	1	0.09 0.04	0.25 0.15	7.1 6.9	4.65 4.55	7.1 6.9	4.65 4.55	0.4	4.8	6	4.8	5.2	0.45	0.46 0.40	0.3 0.2	0.125 0.025	0.07	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT941-2	---	---	---			07-08-22 07-11-14

Fig. 1. Package outline HVQFN112U (SOT941-2)

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3. Legal information

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Date of release: 8 February 2016
